



Material Content Data Sheet



Sales Product Name		TLS715B0EJ V50		Issued		25. September 2017		
MA#		MA001335010						
Package		PG-DSO-8-52		Weight*		83.60 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.642	0.77	0.77	7684	7684
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		435	
	non noble metal	iron	7439-89-6	0.728	0.87		8704	
wire	non noble metal	copper	7440-50-8	29.548	35.34	36.26	353431	362679
	non noble metal	copper	7440-50-8	0.046	0.05	0.05	545	545
	encapsulation	organic material	carbon black	1333-86-4	0.102	0.12		1217
encapsulation	plastics	epoxy resin	-	4.680	5.60		55981	
	inorganic material	silicondioxide	60676-86-0	46.089	55.14	60.86	551292	608490
leadfinish	non noble metal	tin	7440-31-5	0.704	0.84	0.84	8419	8419
plating	noble metal	silver	7440-22-4	0.725	0.87	0.87	8666	8666
glue	plastics	epoxy resin	-	0.074	0.09		879	
	noble metal	silver	7440-22-4	0.221	0.26	0.35	2638	3517
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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